

EMULATED EEPROM MEMORY DEVICE AND CORRESPONDING METHOD

TECHNICAL FIELD

The present invention relates to a method and device to emulate the features of an EEPROM memory device.

5 More specifically, the invention relates to an Emulated EEPROM memory device of the type included in a memory macrocell which is embedded in an integrated circuit comprising also a microcontroller and including a Flash EEPROM memory structure formed by a predetermined number of sectors.

10 The invention relates, particularly but not exclusively, to microcontroller electronic devices having an on-board resident memory. More specifically, the device may be a microcontroller or a microprocessor having a resident (on-board) and integrated memory macrocell circuit.

15 In the embodiment being described by way of example, the memory macrocell includes an embedded Flash memory portion to store programs and update codes for the microcontroller and an embedded EEPROM non-volatile memory portion to store data.

BACKGROUND OF THE INVENTION

As is well known, modern microcontrollers are provided with on-board memory circuits to store both programs and data on the same IC.

20 In this specific technical field there is a felt need to have at least an EEPROM portion of the memory macrocell to be used just as a non-volatile memory for parameter storage and for defining non-volatile pointers of the stored data.

25 However, Flash and EEPROM technologies are not compatible and the higher integration degree and much lower cost of the Flash devices would suggest to realize memory macrocell including just Flash memory cells.

The memory circuit structure should comprises three portions: a main Flash memory portion, a small OTP (One-Time-Programmable) portion and an EEPROM memory portion.

The Flash memory portion should include at least four sectors.

5 Flash and EEPROM portions have respective sense amplifiers so that one memory portion can be read while the other memory portion is written. However, simultaneous Flash and EEPROM write operations are not allowed. Also not allowed is erasing of the EEPROM portion while writing on the Flash portion.

10 Flash memory devices may be electrically erased by erasing the whole memory portion; while the EEPROMs may be erased on a byte by byte basis.

The memory macrocell has a register interface mapped in the memory area. All the operations are enabled through two control registers, one register FCR for the Flash (and OTP) portion operations and another one ECR for the EEPROM portion operations.

15 The status of a write operation inside the Flash portion can be monitored by a dedicated status register.

A known prior art solution allows the above operations by using an EEPROM software emulation addressing two Flash sectors which are dedicated to EEPROM emulation.

20 At each data update a pointer is added to find the new data. When a Flash sector is full all the data are swapped to the other sector. An unused sector is erased in background.

This solution presents good cycling performances in the same few bytes are continuously updated.

25 However, there are also some drawbacks which are listed hereinafter:

the best emulation is obtained by a huge managing software, at least 20 Kbytes, which must be stored in the same memory circuit;

it might be necessary to wait for erase suspend before accessing at the EEPROM for read and write operations;

a long read access time has been found during experimentation.

SUMMARY OF THE INVENTION

A first object of the present invention is that of providing a new method for emulating an EEPROM memory portion by using a Flash memory portion.

5 A further object of the present invention is to provide an innovative system which allows a Flash memory portion to emulate EEPROM byte alterability.

Another object of the present invention is that of providing a memory device comprising a Flash memory portion which may be accessed as a EEPROM memory portion during read, write and erase operations.

10 A further object of the present invention is that of providing a microprocessor or a microcontroller having an on-board memory portion including Flash sectors emulating EEPROM byte alterability.

An embodiment of the invention provides an EEPROM hardware emulation of a Flash memory portion.

15 The embodiment includes an integrated memory device having at least two sectors of a Flash memory structure that are used to emulate EEPROM byte alterability.

20 The feature and advantages of inventive method and device will appear from the following non-limiting description of a preferred embodiment given by way of example with reference to the annexed drawings.

BRIEF DESCRIPTION OF THE DRAWINGS

Figures 1 shows a schematic diagram of a memory macrocell including a Flash memory portion and an EEPROM hardware emulation according to an embodiment of the present invention.

25 Figure 2 shows a schematic diagram of the inside structure of the EEPROM emulated memory portion of Figure 1.

Figure 3 shows a simplified and schematic view in greater detail of the EEPROM portion structure.

Figure 3A shows a simplified and schematic view of a register interface associated with the memory macrocell of Figure 1.

5 Figure 3B reports in a table form the addresses and size of each memory sector of the memory macrocell of Figure 1.

Figures 3C, 3D and 3E show schematic views of a Flash Control Register, an EEPROM Control Register, and a Flash Status Register, respectively;

10 Figure 4 is a high level flow-chart representing the steps of a method in accordance with an embodiment of the present invention;

Figure 4A shows a simplified and schematic view of a register interface associated with the EEPROM emulated portion of Figure 1;

Figure 4B reports in a table form the addresses and size of each EEPROM memory sector.

15 Figures 4C, 4D and 4E show a schematic view of a Flash Control Register, an EEPROM Control Register, and a Flash Status Register, respectively.

Figures 5 to 12 show simplified and schematic views of a series of updating phases concerning the EEPROM sectors of the memory macrocell of Figure 1.

20 Figure 13 is a diagram of the write time versus the memory size for the memory macrocell of Figure 1.

Figure 14 shows a simplified and schematic view of a state machine controlling an address counter inside the memory macrocell of Figure 1.

DETAILED DESCRIPTION

With reference to the annexed drawing, with 1 is globally indicated a 25 memory macrocell which is realized according to an embodiment of the present invention by a Flash EEPROM memory structure including an emulated EEPROM memory portion 2.

The memory macrocell 1 is embedded into an integrated circuit comprising also a microcontroller. The invention is specifically, but not exclusively, provided for an integrated microcontroller having an on-board non-volatile memory portion.

5 However, the principles of the invention may also be applied to an integrated memory circuit structure.

The memory macrocell 1 comprises a main 128 Kbyte Flash memory structure formed by a predetermined number of sectors, two of which are used to emulate EEPROM byte alterability. More specifically 8 Kbyte of the Flash memory 10 portion are used to emulate 1 Kbyte of an EEPROM memory portion.

Four sectors are provided for the Flash memory portion: a first 64 Kbyte sector F0; a second 48 Kbyte sector F1; a third 8 Kbyte sector F2 and a fourth 8 Kbyte sector F3.

15 A fifth 4 Kbyte sector F4 represents and corresponds to a first EEPROM emulated sector E0, while a sixth 4 Kbyte sector F5 represents and corresponds to a second emulated EEPROM sector E1.

An 8 Kbyte test portion 3 of the Flash memory macrocell 1 is provided to store test flags.

20 Sense amplifiers circuit portions 4 and 5 are provided at opposite sides of the memory macrocell 1, as shown in Figure 1.

Those sense amplifiers are connected to a program/erase controller 6 which cooperates with a dedicated registers interface 7 through a RAM buffer 8.

A 256 word ROM 9 is also connected to the controller 6.

25 The first and second EEPROM emulated sectors E0, E1 are each divided in four blocks BLOCK 0, ..., BLOCK3 of the same size. Figure 2 shows schematically the emulated EEPROM structure.

Each block is divided in up to sixty-four pages and each page is formed by sixteen bytes.

It will be appreciated that the sizes and numbers of the sectors, blocks, pages, and bytes indicated herein are exemplary only and other sizes and numbers could be employed for each of those memory portions without departing from the invention.

At each page update, selected page data are moved to the next free block.

5 When a sector is full, all the pages are swapped to the other sector.

Figure 3 shows a simplified and schematic view in which each block includes only four pages instead of the sixty-four pages above mentioned. This simplified layout is used just to explain the EEPROM hardware emulation according to the invention.

10 Now, with specific reference also to the example of figure 5, the page updating procedure will be disclosed.

Each page inside each block must be identified to know in which block the updated page is. In this respect, a group of non-volatile pointers is used.

15 In each EEPROM sector E0, E1 some additional non-volatile memory locations are provided. Those locations are not accessible by the user.

Those locations are 256 bytes for each sector E0, E1 and are more than the amount strictly necessary to store the pointers. Only 66 locations are effectively used; 64 for the page pointers (one for each page) and other two for indicating the updating status of the other sector.

20 The above memory locations are programmed in the single bit mode (bit by bit); in other words, at each updating step different locations are programmed to "0" since in a Flash memory portion it's not possible to overwrite a memory location without a previous erasing of that location, but this would involve losing also the user's information.

25 The registers writing strategy must keep in consideration the fact that when a sector is erased even the registers included in that sector are erased too.

Therefore, the content of non-volatile registers is also stored in volatile memory locations to allow an efficient addressing of the EEPROM user's space.

The erasing phase is a time consuming operation for the periods of time which are normally acceptable for writing an EEPROM allocation. That's why the erasing phase is divided into a number of steps corresponding to the number of blocks, which are four in this example.

5 In this manner the EEPROM sector complementary to the one being updated will be surely erased even in the worst case in which the same page is continuously updated. In other words, after four writing phases a swap on the other sector is required.

10 The specific erasing phase is divided in four steps providing respectively:

- a pre-programming phase to "0" of half a sector;
- a subsequent pre-programming to "0" of the other half sector;
- erasing plus erasing verify on a sample of cells;
- full erasing.

15 Moreover, since the EEPROM updating phase may require a certain number of steps, a one bit flag is set when the updating phase is started and a different one bit flag is set when the updating phase is completed. This facilitates the recovery operation in case of a fault during updating.

20 In the example of Figure 5, the EEPROM sector 0 initially is fully erased (initial content is FFh) and error phase 0, the first pre-programming phase, has been completed to set the bits of the second half (blocks 2 and 3) of the EEPROM sector 1 to zero. Upon receiving an instruction to write 55h into the first location of page 1, the program/erase controller 6 writes the 55h into the first location of page 1 of block 1 rather than the corresponding location of block 0. In addition, the controller 6 performs 25 error phase 1, the second pre-programming phase, to set the bits of the first half (blocks 0 and 1) of the EEPROM sector 1 to zero.

In Figure 6, an AAh is being written into the last location of page 1. Rather than writing it into the block 1, the program/erase controller 6 writes the AAh into page 1 of block 2 and the 55h previously written into page 1 of block 1 is moved

into page 1 of block 2. In addition, the controller 6 performs error phase 2 to erase and erase verify a sample of cells of EEPROM sector 1 (Figure 6 shows all cells being erased because of the simplified example using pages of 4 bytes instead of 16).

5 In Figure 7, the program/erase controller 6 writes 33h, 66h, 99h, and CCh into page 0. Since in the example no data has already been written into page 0, the controller 6 writes the 4 data bytes into page 0 of block 1. In addition, the controller 6 performs error phase 3 to erase all of the bytes of EEPROM sector 1.

10 In Figure 8, AAh, 44h, and 88h are written into the first 3 locations of page 1. The new data are written into page 1 of block 3 and the unchanged AAh in the fourth location of page 1 is moved from block 2 to block 3. No erase is performed on EEPROM sector 1 because it is already fully erased.

15 In Figure 9, 55h is being written into the last location of page 1. The program/erase controller 6 writes the 55h into last location of page 1 of block 0 of EEPROM sector 1 and moves all of the data from EEPROM sector 0 to block 0 of EEPROM sector 1. In addition, the controller 6 performs error phase 0 on EEPROM sector 0 by setting to zero the bytes of blocks 2 and 3 of EEPROM sector 0.

Let's now consider the example of Figure 14 showing a state machine 15 (PEC) controlling an address counter 20 which receives as input control signals CTL_SIGN, INCREMENT coming from the state machine 15.

20 The address counter 20 is output connected to an internal address bus 21 which is inside the memory macrocell 1.

25 The address counter 20 doesn't correspond to the usual address counter included into a Flash memory since it receives also control signals from the state machine 15 in order to control the loading of hard-coded addresses in volatile or non-volatile registers 25. The registers 25 may be read and updated by the microcontroller during a reset phase or by the state machine 15 after an EEPROM update.

The address bus 21 is connected to the input of a 16 byte RAM buffer 22 which is used for the page updating of the EEPROM. This RAM buffer 22 includes also

two additional bytes 23, 24 to store the page address during the page updating phase and the swap step.

When the user's program requires to write one or more byte in the EEPROM memory portion, the RAM buffer 22 is charged. Each charged memory location of the RAM buffer 22 has a supplementary bit TOBEPROG which is set so that the state machine 15 is able to complete the charging phase with "old" data in non-flagged locations by just checking the content of the TOBEPROG bit during a subroutine "Page Buffer Filling" as will be later explained.

The state machine 15 is active for instance in controlling the EEPROM page updating phase through an algorithm which will be disclosed in detail hereinafter.

Flash and EEPROM memory operations are controlled through the register interface 7 mapped in memory, see for instance the segment 22h in Figure 3A.

Flash Write Operations allows one to program (from 1 to 0) one or more bytes or erase (from 0 or 1 to 1) one or more sectors.

EEPROM Write Operations allows to program (from 0 or 1 to 0 or 1) one or more bytes or erase all the memory (from 0 or 1 to 1).

Set Protection Operations allows to set Access, Write or Test Mode Protections.

As previously disclosed, the memory 1 comprises three portions: four main Flash sectors F0, F1, F2 and F3 for code, a small OTP zone included into the Flash and an EEPROM portion 2. Figure 3B reports in a table form the addresses and size of each memory sector.

The last four bytes of the OTP area (211FFCh to 211FFFh) are reserved for the Non-Volatile Protection Registers and cannot be used as storage area.

The Flash memory portion, including the OTP, and the EEPROM have duplicate sense amplifiers 4, 5, so that one can be read while the other is written. However, simultaneous Flash and EEPROM write operations are forbidden.

Both Flash and EEPROM memories can be fetched. Reading operands from Flash or EEPROM memories is achieved simply by using whatever microcontroller addressing mode with the Flash and in the EEPROM memory as source.

Writing in the Flash and in the EEPROM memories are controlled 5 through the register interface 7 as explained hereinafter.

The memory macrocell 1 has a register interface 7 mapped in the memory space indicated with the segment 22h (Figure 3A). All the operations are enabled through two control registers; A FCR (Flash Control Register) for the Flash (and OTP) operations and an ECR (EEPROM Control Register) for the EEPROM 10 operations. Those registers are shown in Figures 3C and 3D respectively,

The status of a write operation inside the Flash memory can be monitored through a dedicated status register: FSR (Flash Status Register) shown in Figure 3E.

1) FLASH MEMORY OPERATIONS

Four Write Operations are available for the Flash memory portion: Byte 15 program, Page Program, Sector Erase and Chip Erase. Each operation is activated by a sequence of three instructions:

20	OR	FCR,	#OPMASK ;	Operation selection
	LD	ADD,	#DATA ;	Address and Data load
	OR	FCR,	#080h ;	Operation start

The first instruction is used to select the desired operation, by setting bits FBYTE, FPAGE, FSECT or FCHIP of FCR. The second instruction is used to choose the address to be modified and the data to be programmed. The third instruction is used 25 to start the operation (set of bit FWMS of FCR).

FWMS bit and the Operation Selection bit of FCR are automatically reset at the end of the Write operation.

Once selected, but non yet started (FWMS bit still reset), one operation can be canceled by resetting the Operation Selection bit. The eventually latched 30 addresses and data will be reset.

In the following, when non differently specified, let's suppose than the Data Page Pointer DPR0 has been set to point to the desired 16 Kbyte block to modify, while DPR1 has been set to point to the Register interface:

5	SPP	#21		;	MMU paged registers
	LD	R241,	#089h	;	Register Interface
	LD	R240,	#000h	;	1st 16K page of Flash 0
	LD	R240,	#001h	;	2nd 16K page of Flash 0
	LD	R240,	#002h	;	3rd 16K page of Flash 0
10	LD	R240,	#003h	;	4th 16K page of Flash 0
	LD	R240,	#004h	;	1st 16K page of Flash 1
	LD	R240,	#005h	;	2nd 16K page of Flash 1
	LD	R240,	#006h	;	3rd 16K page of Flash 1
	LD	R240,	#007h	;	Flash 2 and Flash 3
15	LD	R240,	#084h	;	OTP

A) Byte Program

The Byte program operation allows to program 0s in place of 1s.

20	OR	0400h,	#010h	;	Set FBYTE in FCR
	LD	03CA7h,	#D6h	;	Address and Data load
	OR	0400h,	#080h	;	Set FWMS in FCR

The first instruction is used to select the Byte Program operation, by setting bit FBYTE of FCR. The second instruction is used to specify the address and the data for the byte programming. The third instruction is used to start the operation (set of bit FWMS of FCR).

If more than one pair of address and data are given, only the last pair is taken into account. It's not necessary to use a word-wide instruction (like LDW) to enter address and data: only one byte will be programmed, but it is unpredictable whether it will be the low or the high part of the word (it depends on the addressing mode chosen).

30 After the second instruction the FBUSY bit of FCR is automatically set. FWMS, FBYTE and FBUSY bits of FCR are automatically reset at the end of the Byte program operation (10 μ s typical).

The Byte Program operation is allowed during a Sector Erase Suspend, and of course not in a sector under erase.

B) Page Program

The Page Program operation allows to program 0s in place of 1s. From 1 to 16 bytes can be stored in the internal Ram before starting the execution.

5	OR	0400h,	#040h	; Set FPAGE in FCR
	LD	028B0h,	#0F0h	; 1st Address and Data
	LD	028B1h,	#0E1h	; 2nd Add and Data (Opt.)
	LD	028B2h,	#0D2h	; 3rd Add and Data (Opt.)
		
10	LD	028Bxh,	#0xxh	; xth Add and Data (Opt.)
		
	LD	028beh,	#01Eh	; 15th Add and Data (Opt.)
	LD	028bfh,	#00Fh	; 16th Add and Data (Opt.)
	OR	0400h,	#080h	; Set FWMS in FCR

15 The first instruction is used to select the Page Program operation, by setting bit FPAGE of FCR. The second instruction is used to specify the first address and the first data to be programmed. This second instruction can be optionally followed by up to 15 instructions of the same kind, setting other addresses and data to be programmed. All the addresses must belong to the same page (only the four LSBs of address can change). Data contained in page addresses that are not entered are left unchanged. The third instruction is used to start the operation (set of bit FWMS of FCR).

20 If one address is entered more than once inside the same loading sequence, only the last entered data is taken into account. It is allowed to use word-wide 25 instructions (like LDW) to enter address and data.

After the second instruction the FBUSY bit of FCR is automatically set. FWMS, FPAGE and FBUSY bits of FCR are automatically reset at the end of the Page Program operation (160 us typical).

The Page Program operation is not allowed during a Sector Erase 30 Suspend.

C) Sector Erase

The Sector Erase operation allows to erase all the Flash locations to 0ffh. From 1 to 4 sectors to be simultaneously erased can be entered before to start the

execution. This operation is not allowed on the OTP area. It is not necessary to pre-program the sectors to 00h, because this is done automatically.

5	PP	#21	;	MMU paged registers	
	LD	R240,	#000h	;	1st 16K page of Flash 1
	LD	R242,	#004h	;	1st 16K page of Flash 2
	LD	R243,	#007h	;	Flash 2 and Flash 3

First DPR0 is set to point somewhere inside the Flash sector 0, DPR2 inside Flash sector 1, DPR3 inside Flash sectors 2 and 3. DPR1 continues to point to the 10 Register interface.

15	OR	04000h,	008h	;	Set FSECT in FCR
	LD	00000h,	000h	;	Flash 0 selected
	LD	08000h,	000h	;	Flash 1 selected (Opt. 9)
	LD	0C000h,	000h	;	Flash 2 selected (Opt. 9)
	LD	0E000h,	000h	;	Flash 3 selected (Opt. 9)
	OR	04000h,	080h	;	Set FWMS in FCR

The first instruction is used to select the Sector Erase operation, by 20 setting bit FSECT of FCR. The second instruction is used to specify an address belonging to the first sector to be erased. The specified data is "don't care." This second instruction can be optionally followed by up to three instructions of the same kind, selecting other sectors to be simultaneously erased. The third instruction is used to start the operation (set of bit FWMS of FCR).

Once selected, one sector cannot be deselected. The only way to deselect 25 the sector, is to cancel the operation, by resetting bit FSECT. It is allowed to use word-wide instructions (like LDW) to select the sectors.

After the second instruction the FBUSY bit of FCR is automatically set. FWMS, FSECT and FBUSY bits of FCR are automatically reset at the end of the Sector Erase operation (1.5 s typical).

30 The Sector Erase operation can be suspended in order to read or to program data in a sector not under erase. The Sector Erase operation is not allowed during a Sector Erase Suspend.

C.1) Sector Erase Suspend/Resume

The Sector Erase Suspend is achieved through a single instruction.

OR 0400h, #004h ; Set FSUSP in FCR

This instruction is used to suspend the Sector Erase operation, by setting 5 bit FSUSP of FCR. The Erase Suspend operation resets the Flash memory to normal read mode (automatically resetting bits FWMS and FBUSY) in a maximum time of 15 μ s. Bit FSECT of FCR must be kept set during the Sector Erase Suspend phase: if it is software reset, the Sector Erase operation is cancelled and the content of the sectors under erase is not guaranteed.

10 When in Sector Erase Suspend the memory accepts only the following operations: Read, Sector Erase Resume and Byte program. Updating the EEPROM memory is not possible during a Flash Sector Erase Suspend.

The Sector Erase operation can be resumed through two instructions:

15 AND 04000h, #0FBh ; Reset FSUSP in FCR
OR 04000h, #080h ; Set FWMS in FCR

The first instruction is used to end the Sector Erase Suspend phase, by resetting bit FSUSP of FCR. The second instruction is used to restart the suspended 20 operation (set of bit FWMS of FCR). After this second instruction the FBUSY bit of FCR automatically set again.

D) Chip Erase

The Chip Erase operation allows to erase all the Flash locations to 0ffh. This operation is simultaneously applied to all the 4 Flash sectors (OTP area excluded). It is not necessary to pre-program the sectors to 00h, because this is done automatically.

25 OR 04000h, #020h ; Set FCHIP in FCR
OR 04000h, #080h ; Set FWMS in FCR

The first instruction is used to select the Chip Erase operation, by setting 30 bit FCHIP of FCR. The second instruction is used to start the operation (setting of bit FWMS of FCR).

It is not allowed to set the two bits (FCHIP and FWMS) with the same instruction.

After the second instruction the FBUSY bit of FCR is automatically set. FWMS, FCHIP and FBUSY bits of FCR are automatically reset at the end of the Chip 5 Erase operation (3 s typical).

The Chip Erase operation cannot be suspended. The Chip Erase operation is not allowed during a Sector Erase Suspend.

2) EEPROM MEMORY OPERATIONS

Two Write Operations are available for the EEPROM memory: Page 10 Update and Chip Erase. Each operation is activated by a sequence of three instructions:

10	OR	ECR,	#OPMASK ;	Operation selection
	LD	ADD,	#DATA ;	Address and Data load
15	OR	ECR,	#080h ;	Operation start

The first instruction is used to select the desired operation, by setting bits EPAGE or ECHIP of ECR. The second instruction is used to choose the address to be modified and the data to be programmed. The third instruction is used to start the operation (set of bit EWMS of ECR).

EWMS bit and the Operation Selection bit of ECR are automatically 20 reset at the end of the Write operation.

Once selected, but not yet started (EWMS bit still reset), one operation can be canceled by resetting the Operation Selection bit. The eventually latched addresses and data will be reset.

In the following, when not differently specified, let's suppose that the 25 Data Page Pointer DPR0 has been set to point to the EEPROM to modify, while DPR1 has been set to point to the Register interface:

30	SPP	#21	;	MMU paged registers
	LD	R241,	#089h ;	Register Interface
	LD	R240,	#088h ;	EEPROM

It's important to note that the EEPROM operations duration are related to the EEPROM size, as shown in the table of Figure 4B.

A) Page Update

The page Update operation allows to write a new content. Both 0s in 5 place of 1s and 1s in place of 0s. From 1 to 16 bytes can be stored in the internal Ram buffer before to start the execution.

	OR	04001h,	#040h	;	Set EPAGE in ECR
	LD	001C0g,	#0F0h	;	1st Address and Data
10	LD	001C1h,	#0E1h	;	2nd Add and Data (opt.)
	LD	001C2h,	#0D2h	;	3rd Add and Data (opt.)
			
	LD	001Cxh,	#0xxh	;	xth Add and Data (opt.)
			
15	LD	001ceh,	#01Eh	;	15th Add and Data (opt.)
	LD	001cfh,	#00Fh	;	16th Add and Data (opt.)
	OR	04001h,	#080h	;	Set EWMS in ECR

The first instruction is used to select the Page Update Operation, by 20 setting bit EPAGE of EVR. The second instruction is used to specify the first address and the first data to be modified. This second instruction can be optionally followed by up to 15 instructions of the same kind, setting other addresses and data to be modified. All the addresses must belong to the same page (only the four LSBs of address can change). Data contained in page addresses that are not entered are left unchanged. The third instruction is used to start the operation (setting of bit EWMS of ECR).

25 If one address is entered more than once inside the same loading sequence, only the last entered data is taken into account. It is allowed to use word-wide instructions (like LDW) to enter address and data.

After the second instruction the EBUSY bit of ECR is automatically set. 30 EWMS, EPAGE and EBUSY bits of ECR are automatically reset at the end of the Page Update operation (30 ms typical).

The Page Update operation is not allowed during a Flash Sector Erase Suspend.

B) Chip Erase

The Chip Erase operation allows to erase all the EEPROM locations to 0ffh.

5 OR 04001h, #020h ; Set ECHIP in ECR
 OR 04001h, #080h ; Set EWMS in ECR

The first instruction is used to select the Chip Erase operation, by setting bit ECHIP of ECR. The second instruction is used to start the operation (setting of bit EWMS of ECR).

10 It is not allowed to set the two bits (ECHIP and EWMS) with the same instruction.

After the second instruction the EBUSY bit of ECR is automatically set. EWMS, ECHIP and EBUSLY bits of ECR are automatically reset at the end of the Chip Erase operation (70 ms typical).

15 The Chip Erase operation cannot be suspended. The Chip Erase operation is not allowed during a Flash Sector Erase Suspend.

3) Protections Operations

Only one Write Operation is available for the Non Volatile Protection Registers: Set Protection operation allows to program 0s in place of 1s. From 1 to 4 bytes can be stored in the internal Ram buffer before to start the execution. This 20 operation is activated by a sequence of 3 instructions:

OR FCR, #002h ; Operation selection
LD ADD, #DATA ; Address and Data load
OR FCR, #080h ; Operation start

25 The first instruction is used to select the Set protection operation, by settling bit PROT of FCR. The second instruction is used to specify the first address and the first data to be programmed. This second instruction can be optionally followed by up to three interactions of the same kind, setting other addresses and data to be programmed. All the addresses must belong to the Non Volatile Protection registers 30 (only the two LSBs of address can change). Protection Registers contained in addresses that are not entered are left unchanged. Content of not selected bits inside selected

addresses are left unchanged, too. The third instruction is used to start the operation (setting of bit FWMS of FCR).

5 If one address is entered more than once inside the same loading sequence, only the last entered data is taken into account. It is allowed to use word-wide instructions (like LDW) to enter address and data.

After the second instruction the FBUSY bit of FCR is automatically set. FWMS, PROT and FBUSY bits of FCR are automatically reset at the end of the Set protection operation (40 μ s typical).

10 Once selected, but not yet started (FWMS bit still reset), the operation can be canceled by resetting PROT bit. The eventually latched addresses and data will be reset.

The Set Protection operation is not allowed during a Sector Erase Suspend.

15 In the following, when not differently specified, let's suppose that the Data Page pointer DPR0 has been set so to point to the OTP area to modify, while DPR1 has been set so to point to the Register interface:

20 SPP #21 ; MMU paged registers
LD R241, #089h ; Register Interface
LD R240, #084h ; OTP

There are three kinds of protections: access protection, write protections and test modes disabling.

3.1) Non-Volatile Registers

25 The protection bits are stored in the last four locations of the OTP area (from 211FFCh to 211FFFh), as shown in Figure 4A. All the available protections are forced active during reset, then in the initialization phase they are read from the OTP area.

30 The four non-volatile registers used to store the protection bits for the different protection features are one time programmable (OTP).

The access to these registers is controlled by the protections related to the OTP area where they are mapped.

3.2) Set Access Protections

The Access Protections are given by bits APRA, APRO, APBR, APEE,

5 APEX of NVAPR.

OR	04000h,	#002h	;	Set PROT in FCR
LD	01FFCh,	#0F1h	;	Prog WPRS3-1 in NVWPR
OR	04000h,	#080h	;	Set FWMS in FCR

10 The first instruction is used to select the Set Protection operation, by setting bit PROt of FCR. The second instruction is used to specify the NVAPR address and the new protection content to be programmed. The third instruction is used to start the operation (setting of bit FWMS of FCR).

3.3) Set Write Protections

15 The Write Protections are given by bits WPBR, WPEE, WPRS3-0 of NVWPR.

OR	04000h,	#002h	;	Set Prot in FCR
LD	01FFDh,	#0F1h	;	Prog WPRS3-1 in NVWPR
20 OR	04000h,	#080h	;	Set FWMS in FCR

The first instruction is used to select the Set Protection operation, by setting bit PROT of FCR. The second instruction is used to specify the NVWPR address and the new protection content to be programmed. The third instruction is used to start the operation (setting of bit FWMS of FCR).

25 The Write Protections can be temporary disabled by executing the Set Protection operation and writing 1 into these bits.

OR	01000h, #002h	;	Set Prot in FCR	
LD	01FFDh,	#0F2h	;	Prog WPRS0 in NVWPR
30 OR	01000h, #080h	;	;	Temp Unprotected WPRS1
				Set FWMS in FCR

The non-volatile content of the temporary unprotected bit remains unchanged, but now the content of the temporary unprotected sector can be modified.

To restore the protection it needs to reset the micro or to execute another Set protection operation and write 0 into this bit.

3.4) Disable Test Modes

The Test Mode Protections are given by bits TMDIS and PWOK of

5 NVWPR.

OR	04000h, #002h ;	Set PROT in FCR
LDW	01FFEh, #05A7Ch ;	Prog NVPWD1-0
OR	04000h, #080h ;	Set FWMS in FCR

10 The first instruction is used to select the Set Protection operation, by setting bit PROT of FCR. The second instruction must be word-wide and it is used to specify the NVPWD1-0 address and the password to be programmed. The third instruction is used to start the operation (setting of bit FWMS of FCR). The second instruction automatically forces TMDIS bit of NVWPR to be programmed.

15 Once disabled the Test Modes can be enabled again only by repeating the disable test mode sequence with the right Password. If the given data is matching with the programmed password in NVPWD1-0, bit PWOK of NVWPR is programmed and Test Modes are enabled again.

20 If the given data is not matching, one of bits PWT2-0 of NVAPR is programmed. After three unmatching trials, when all bits PWT2-0 are programmed, Test Modes are disabled for ever.

25 Just as an example, hereinafter a program erase controller algorithm for the Flash/EEPROM macrocell 1 is reported. This algorithm uses a call subroutine instruction named CAL and return from subroutine instruction named RET with four nested levels allowed.

Available Instructions:

ALT	input ; Wait for input at 1
CMP	input ; Compare input and set a Flag if 1 (x3 instructions: three CMPi are existing, CMP1, CMP2, CMP3)
30	JMP label ; Jump to label
JIF	label ; Jump to label if Flag = 1

JFN label ; Jump to label if Flag = 0
CAL label ; Call subr. (Store PC, Inc. SP and Jump to label)
CLF label ; Call subr. if Flag = 1
RET ; Return from subr. (Dec. SP and Jump to stored PC)
5 STO output ; Set output at 1 (x5 instructions: 5 STO*i* instr. are
existing, STO1, STO2, ... STO5) {this instr. is used to activate any
Output signal of the PEC};

Input Variables:

10 NOTHING = No variables => Realize a NOP with CMP NOTHING;
ALL0 = All0 phase active
ALLERASED = All sectors erased
DATOOK = Data verified equal to the target
ENDPULSE = End of Prog or Erase pulse
15 ERSUSP = Erase Suspended
LASTADD = Last Row or Column
LASTSECT = Last Sector
MAXTENT = Reached maximum tentative number allowed
NORMOP = Normal Read conditions restored
20 SOFTP = Soft Program phase active
SUSPREQ = Erase Suspend request pending
TOBEMOD = Sector to be erased or byte to be programmed
VPCOK = Verify voltage reached by Vpcx;
BYTERCY_FF = Flash Byte Prog operation active or RECYCLE test mode
25 CHIPER_EE = EEPROM Chip Erase operation active
CSERASE_FF = Flash Sector/Chip Erase operation active
NEWERPH0 = Erase phase 1-3 active
NEWERPH1 = Erase phase 2-3 active
NEEDERASE = Unused sector erase needed
30 NEEDSWAP = Sector Swap needed
PAGEPG_EE = EEPROM Page Update operation active
PAGENSP_FF = Flash Page Prog operation active or NOSOFTPtest mode
SELPAGE = Selected Page to update
SWAPFAIL = Swap error => autosuspend needed;

Output Variables:

NOTHING = No variables => Used to reset other variables;
ALL0 = Start/Stop All0 phase (toggle)
5 CUIRES = Reset Command Interface and PEC
ERASE = Start/Stop Erase phase (toggle)
HVNEG = Start Erase pulse
INCCOLM = Increment Column Address
INCROW = Increment Row Address
10 INCSECT = Increment Sector Address
INCTENT = Increment tentative number
LOADADD = Load column address from RAM BUFFER
LOADSECT = Load sector address from RAM BUFFER
PROGRAM = Start Prog pulse
15 READSUSP = Stop the clock during erase suspend
RESFLAG = Eliminate current sector from the list to be erased
SOFTP = Start/Stop Soft Program phase (toggle)
STOREADD = Store column address in RAM BUFFER
SWXATVCC = Switch Vpcx at Vcc (read voltage)
20 VERIFY = Set Verify mode
VPCYON = Switch On/Off Vpcy pump (toggle);
ENDSWAP = Reset NEEDSWAP (toggle)
FORCESWAP = Force NEEDSWAP=1 (toggle)
INCPAGE = Increment Page address
25 LDDATA = Load data from RAM buffer
LDNVCSS = Load NVCSS address (from hardware)
LDNVESP = Load NVESP address (from hardware)
LDOLDSECT = Load Old sector address (from hardware)
LDPAGE = Load Page address from RAM BUFFER
30 LDPAGE2 = Load Page address from RAM BUFFER (for Sector Swap)
LDVCSS = Load VCSS address (from hardware)
LDVESP = Load VESP address (from hardware)
PAGE = Start/Stop Page Program phase (toggle)
READ = Set/Reset read conditions (toggle)

STOREDATA = Store read data into the RAM buffer
STOREPAGE = Store page address in RAM BUFFER
STOREPAGE2 = Store page address in RAM BUFFER (for Sector Swap)
STOREPROT = Store Protection data into the RAM buffer
5 STORESECT = Store sector address in RAM BUFFER
SWAP = Set/Reset Sector Swap phase (toggle)
WRITEVS = Write Volatile Status;

Possible Operations:

10 Flash Byte Program (1 nesting level)
Flash Page Program (2 nesting levels)
Flash Chip/Sector Erase (3 nesting levels)
Flash Byte Program while Erase Suspend (4 nesting levels)
Set Protections (2 nesting levels) EEPROM Page Update
15 EEPROM Chip Erase (4 nesting levels)
CODE SIZE = 251 lines;

In this example, only EEPROM Page Update will be described

MAIN PROGRAM:
20 CMP PAGEPG_EE ; EEPROM Chip Update op. selected ?
JIF epgupd ; If yes jump to EEPROM Chip update routine
JMP main ; If no, then loop

SUBROUTINES:

1) SDELAY (the PEC clock is used to count a delay for analog signals settling)
25 CMP NOTHING ; NOP: delay cycle
RET ; 4 NOP + 1 CAL + 1 RET = 6 NOP

2) PROGRAM 1 BYTE (every byte is continuously programmed up to a positive verify

test)
sbytepg

5 STO VERIFY ; Verify Data to be programmed
CMP DATOOK ; Compare read data with 00h
JIF sbpend ; If DATOOK=1 => Return (the data is already OK)
STO PROGRAM ; If DATOOK=0 => Apply Prog pulse
ALT ENDPULSE ; Wait for end of Prog pulse
10 STO INCTENT ; If no Increment tentative number
CMP MAXTENT ; Compare tentative number with maximum allowed
JFN sbytepg ; If MAXTENT=0 => Retry
sbpend RET ; If MAXTENT=1 || DATOOK=1 => Return

15 3) PROGRAM 1 PAGE

spagepg

STO LDDATA ; Read Data and flag TOBEPORG from RAM buffer
CMP TOBEMOD ; Byte to be programmed?
JFN sppincc ; If no increment column
20 sppbyte
CAL sbytepg ; Byte Program
sppincc
STO INCCOLM ; Increment Column address
CMP LASTADD ; Last column ?
25 JFN spagepg ; If no restart program
RET ; If yes Return

4) PROGRAM 1 SECTOR

sssectpg

30 CAL sbytepg ; Byte Program
STO INCROW ; Increment row
CMP LASTADD ; Last Row ?

```
JFN    ssectpg ; If no continue All0
CMP    NOTHING ; NOP: delay cycle
STO    INCCOLM ; Increment Column address
CMP    LASTADD ; Last column ?
5     JFN    ssectpg ; If no program again
      RET    ; If yes Return
```

5) ERASE VERIFY 1 SECTOR (the sector is erased, read and verified byte after byte and after every erasing pulse starting from the last non erased byte; the subroutine 10 terminates when the last byte of the sector is erased)

```
servfy
STO    VERIFY   ; Verify Data to be erased
CMP    DATOOK  ; Compare read Data with 0FFh
JFN    sevend  ; If DATOOK=0 => Return
15    STO    INCROW ; If DATOOK=1 => Increment Row
      CMP    LASTADD ; Last Row ?
      JFN    servfy ; If no continue Erase Verify phase
      STO    INCCOLM ; If yes increment Column address
      CMP    LASTADD ; Last Column ?
20    JFN    servfy ; If no continue Erase Verify phase
      STO    RESFLAG ; If yes the current sector is erased
      sevend RET    ; Return
```

EEPROM ROUTINES

25 1) PAGE BUFFER FILLING. This routine is used to fill all not selected addresses of the selected page with the old data written in those locations. Old Data are read from the old locations (using actual EESECT and EEBCK<1:0>, the Volatile registers) using normal read conditions (Vpcx = 4.5V) forced through signal READ.

30 Once Stored the old data in Ram, the local flag TOBEPROG for that byte is automatically set.

ebufffil

```
STO      READ      ; Enter Read mode conditions
ebfloop
STO      LDDATA    ; Read flag TOBEPROG from RAM buffer
CMP      TOBEMOD   ; Byte to be programmed ?
5       JIF       ebfinc  ; If yes increment column
STO      VERIFY    ; If no Read Old Data (STO3)
STO      STOREDATA ; Store Old Data in Ram Buffer (STO2)
ebfinc
STO      INCCOLM  ; Increment Column address (STO5)
10      CMP       LASTADD ; Last column ?
JFN      ebfloop  ; If no continue RAM filling
STO      READ      ; If yes exit Read mode
RET      ; Return
```

15 2) NON VOLATILE STATUS PROGRAM. This routine is used to program the Non Volatile Status Pointers NVESP, NVCSS0, NVCSS1.

```
estprg
CAL      sbytepg  ; Non Volatile Status Program
CMP      NOTHING   ; NOP: delay cycle
20      RET      ; Return
```

3) PAGE PROGRAM. This routine is used to program a Page taking the data from the RAM buffer. At first not selected page address in the Ram buffer are filled with the last valid data. Then the VIRG bit in NVESP is programmed to notify that the page program operation is started. Then after the page programming, the USED bit in NVESP is programmed to notify that the operation is concluded. At the end also the Volatile Block Pointers are updated

```
epagepg
STO      STOREPAGE ; Store current Page Address in RAM
30      CAL       ebufffil ; Fill-in not selected page address
STO      LDNVESP  ; Load New NVESP address for current page
CAL      estprg   ; NVESP Program (VIRG bit)
STO      LDPAGE   ; Load New Page address from RAM
```

```
CAL     spagepg    ; Page Program
STO     LDNVESP    ; Load New NVESP address for current page
CAL     estprg     ; NVESP Program (USED bit)
STO     LDVESP     ; Load VESP address for current page (STO2)
5      STO     WRITEVS    ; Write Volatile Status BCK<1:0> (STO3)
RET     ; Return
```

4) SECTOR SWAP. This routine is used when in the current sector the 4 blocks for the selected page are already used. In this case the selected page is programmed in the new 10 sector and all the other unselected pages must be swapped to the new sector.

SWAP=1 forces TOBEPROG=0 => in ebufffil routine all the Page data are copied into the RAM buffer

CHIPER_EE=1 forces TOBEPROG=1 => in ebufffil routine all the data in the Ram buffer are kept at FFh (reset value).

```
15    CHIPER_EE=1 forces SELPAGE=0 => no page selected
      esecswp
      STO     SWAP,PAGE ; Enter Sector Swap (STO4)
      esspage
      STO     LDPAGE2    ; Read selected page address from RAM (STO1)
20    CMP     SELPAGE    ; Current page is the selected for update ?
      JIF     essincp    ; If yes increment page
      CAL     epagepg    ; If no Page Program
      essincp
      STO     INCPAGE    ; Increment Page
25    CMP     LASTADD    ; Last Page ?
      JFN     esspage    ; If no swap current page
      CMP     SWAPFAIL    ; Swap fail ?
      JIF     sexit      ; If yes autosuspend
      STO     SWAP,PAGE    ; Exit Sector Swap phase
30    RET     ; Return
```

5) PROGRAM ALL0. This routine is used for program All0. This routine automatically program bit ACT of unused sector when the sector swap is done.

 eall0

```
    STO    ALL0      ; Enter All0 phase (STO4)
5   STO    LDOLDSECT ; Load Old Sector address (STO1)
    CAL    ssectpg   ; Sector Program
    STO    ALL0      ; Exit All0 phase
    RET      ; Return
```

10 6) ERASE. This routine is used for erase. Erase verify is made before the first erase pulse, since during Erase phase 3, the initial cells status is unknown.

 eerase

```
    STO    ERASE      ; Enter Erase phase (STO4)
    STO    LDOLDSECT ; Load Old Sector address (STO1)
15  eervfy
    CAL    servfy    ; Erase Verify on all sector
    CMP    ALLERASED ; All sector erased ?
    JIF    eerend    ; If yes exit erase phase
    eerpul
20  STO    HVNEG      ; If no apply Erase pulse
    ALT    ENDPULSE   ; Wait for end of Erase pulse
    CMP    NOTHING    ; NOP: reset the counter when HVNEG=1
    STO    INCTENT   ; Increment tentative number
    CMP    MAXTENT   ; Compare tentative number with maximum
25  allowed
    JFN    eervfy    ; If MAXTENT=0 => erase verify
    eerend
    STO    ERASE      ; If MAXTENT=1 => exit Erase phase
    RET      ; Return
```

30

7) SECTOR ERASE. This routine is used to enter the needed erase phase on the unused sector, as explained by the following table:

 EPH<3:0> EEERPH<1:0> NEWERPH<1:0> NEEDSWAP NEEDERASE Er. Phase

0000	11	00	0	0	None
0000(1111)	11	00	1	1	0
1110	00	01	0	1	1
1100	01	10	0	1	2
5	1000	10	11	0	1
					3

Erase phase 0 makes the All0 on the second half (status

included) (second half is programmed first just because it includes at the end of its 'address space' the NV status, whose bits must be programmed as soon as possible)

10 Erase phase 1 makes the All0 on the first half.

Erase phase 2 makes the Erase with verification of status only

Erase phase 3 completes the Erase
esecter

```
STO LDNVCSS ; Load NVCSS0 address
15 CAL estprg ; NVCSS0 Program (bit EPHS<3:0>)
CMP NEWERPH1 ;
JFN eseph01 ; If NEWERPH<1:0>=0X => Enter Erase Phase 0-1
CAL eerase ; If NEWERPH<1:0>=1X => Enter Erase Phase 2-3
CMP NEWERPH0 ;
20 JFN eseend ; If NEWERPH<1:0>=10 => Exit Erase Phase 2-3
eseph01
CAL eall0 ; Program All0 (needed before any erase)
eseend
STO LDNVCSS ; Load NVCSS0 address
25 CAL estprg ; NVCSS0 Program (bit EPHE<3:0>)
STO LDVCSS ; Load VCSS0 address (STO2)
STO WRITEVS ; Write Volatile Status ERPH<1:0> (STO3)
CMP NEEDSWAP ;
JFN eseret ; If NEEDSWAP=0 => exit Sector Erase
30 STO ENDSWAP ; If NEEDSWAP=1 => ENDSWAP resets NEEDSWAP
JMP eseend ; Program NVCSS1 (CUR bit) and VCSS1 (EESECT)
eseret
```

RET ; Return

8) PAGE UPDATE. This routine is used to handle all the data transfers between blocks and sectors when an update of a page of the EEPROM is needed

5 epgupd

ALT	VPCOK	; Wait for Vpcx verify voltage (was Read mode)
STO	STOREPAGE2	; Store Page address in RAM (Sect Swap) (STO2)
STO	PAGE	; Enter Page Program phase (STO4)
CAL	epagepg	; Selected Page Program
10	STO	PAGE ; Exit Page Program phase
	CMP	NEEDSWAP ; EEPROM Sector Swap needed ?
	CLF	esecswp ; If yes Sector Swap
	CMP	NEEDERASE ; Unused Sector Erase needed ?
	CLF	esecter ; Unused Sector Erase
15	JMP	sexit ; Exit Page Update

The memory device and the method according to the invention allow a totally hardware emulation of an EEPROM memory portion.

No access differences are detectable between the emulated memory portion according to the invention and a standard EEPROM memory.

20 An immediate EEPROM access is available during the reading and writing phases of the emulated memory portion 2.

A further advantage is given by the Flash code execution running during EEPROM modify phase.

From the foregoing it will be appreciated that, although specific 25 embodiments of the invention have been described herein for purposes of illustration, various modifications may be made without deviating from the spirit and scope of the invention. Accordingly, the invention is not limited except as by the appended claims.